

Title (en)

SOLDER ALLOY, SOLDERING METHOD AND COMPONENT

Title (de)

LOTLEGIERUNG, LOTVERFAHREN UND BAUTEIL

Title (fr)

ALLIAGE DE BRASAGE, PROCÉDÉ DE BRASAGE ET PIÈCE CORRESPONDANTE

Publication

**EP 2558244 A2 20130220 (DE)**

Application

**EP 10713921 A 20100412**

Priority

EP 2010054756 W 20100412

Abstract (en)

[origin: US2013045129A1] A solder alloy including a base material, a solder, and an additive is provided. The solder alloy has the following formula:  $(1-x-y)*\text{base material}+x*\text{solder}+y*\text{additive}$ , where  $0.2 \leq x \leq 0.8$  and  $0 \leq y < 0.8$  and also  $(y < 1-x) < (1-x)$ . The base material includes chromium, cobalt, aluminum, and tungsten. The solder includes chromium, cobalt, aluminum, tungsten, germanium and/or gallium and nickel. The additive may include boron, zirconium, hafnium, niobium, and carbon.

IPC 8 full level

**B23K 35/00** (2006.01); **F01D 5/00** (2006.01)

CPC (source: EP US)

**B23K 35/30** (2013.01 - EP US); **F01D 5/005** (2013.01 - EP US); **F05D 2230/238** (2013.01 - EP US); **Y02T 50/60** (2013.01 - US)

Citation (search report)

See references of WO 2011127958A2

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